

Fig. 1

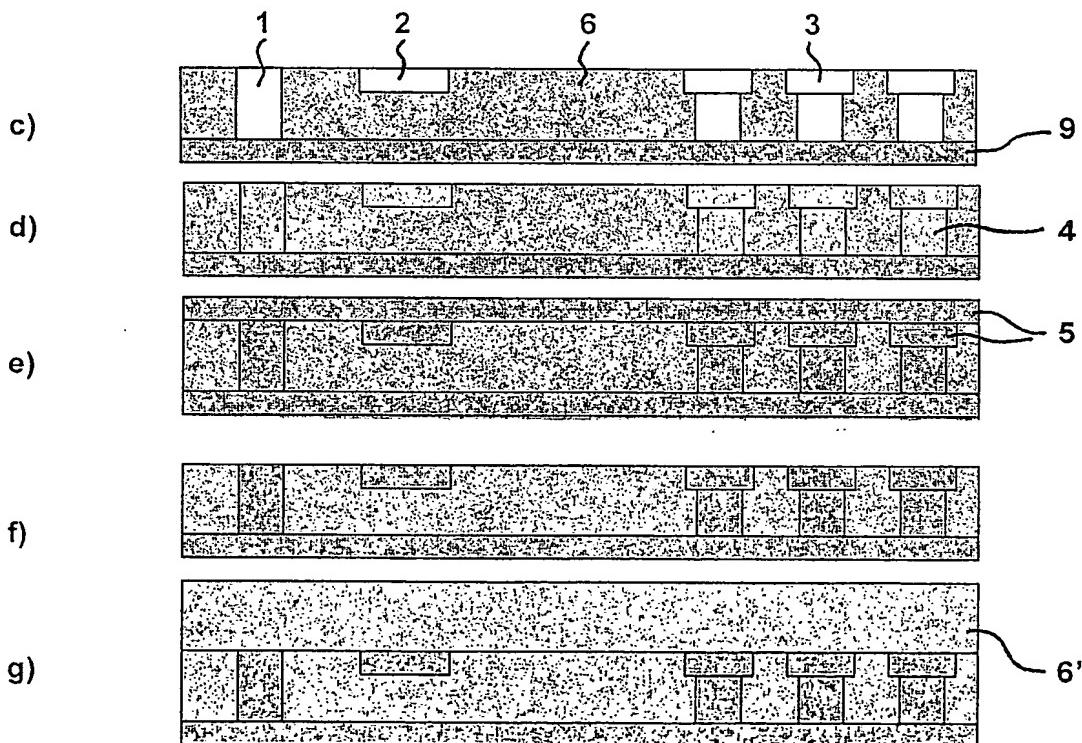


Fig. 2

BEST AVAILABLE COPY

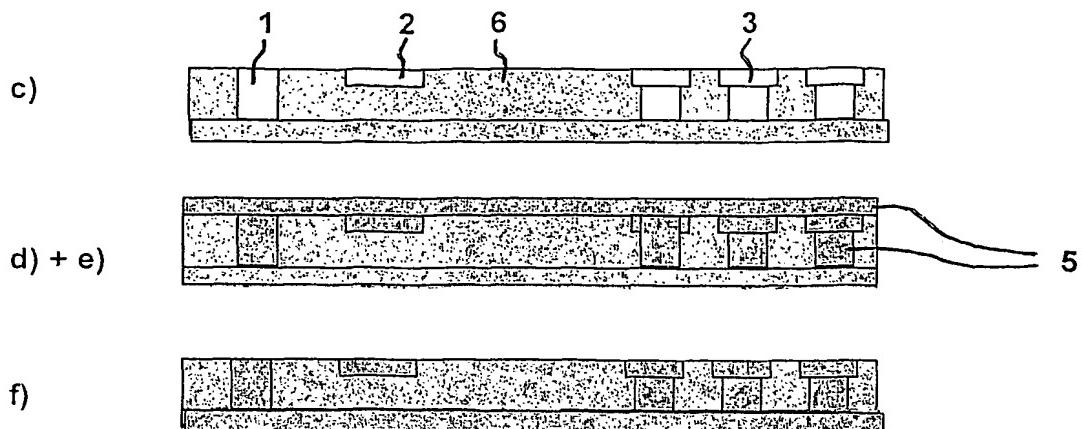


Fig. 3

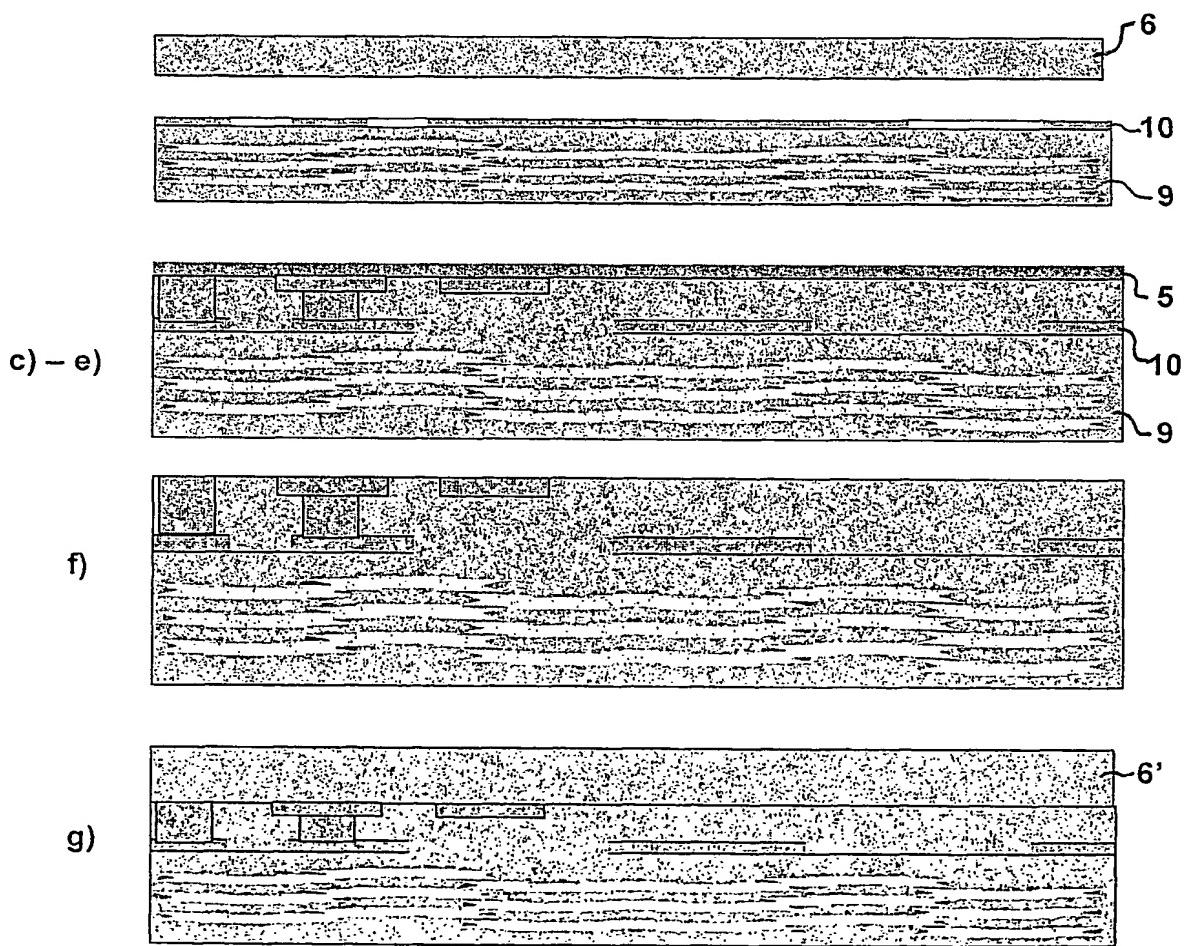


Fig. 4

BEST AVAILABLE COPY

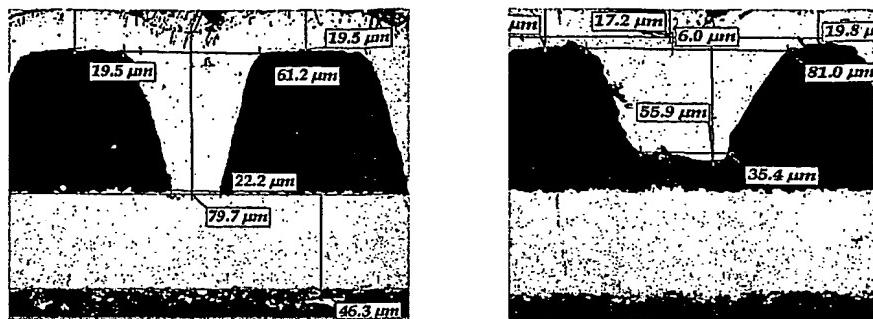


Fig. 5

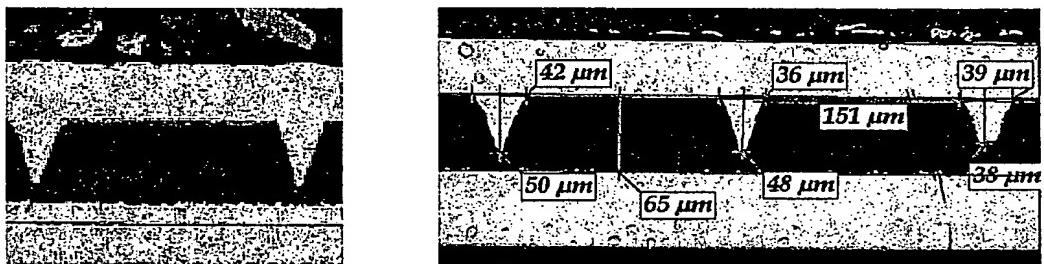


Fig. 6

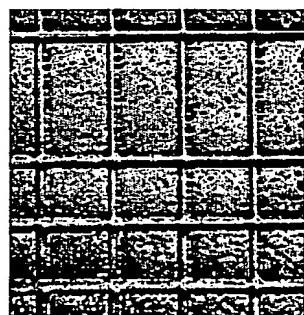


Fig. 7

BEST AVAILABLE COPY

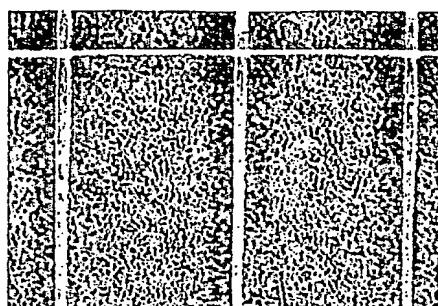


Fig. 8

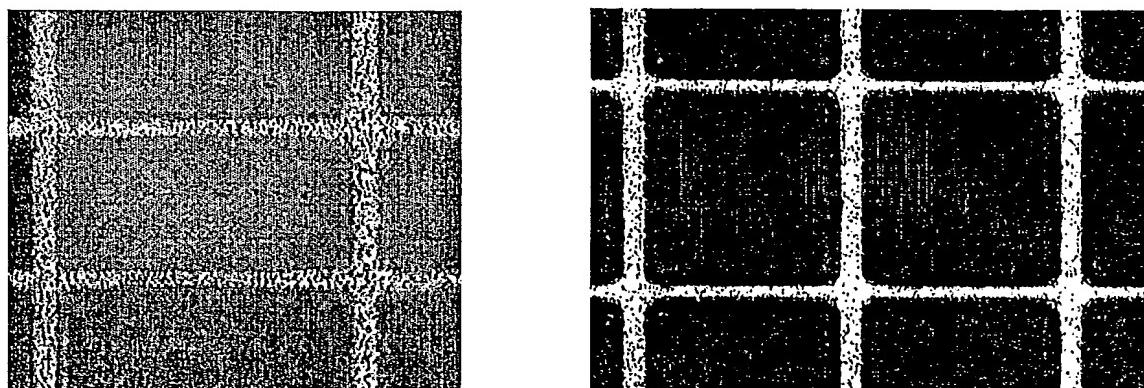


Fig. 9

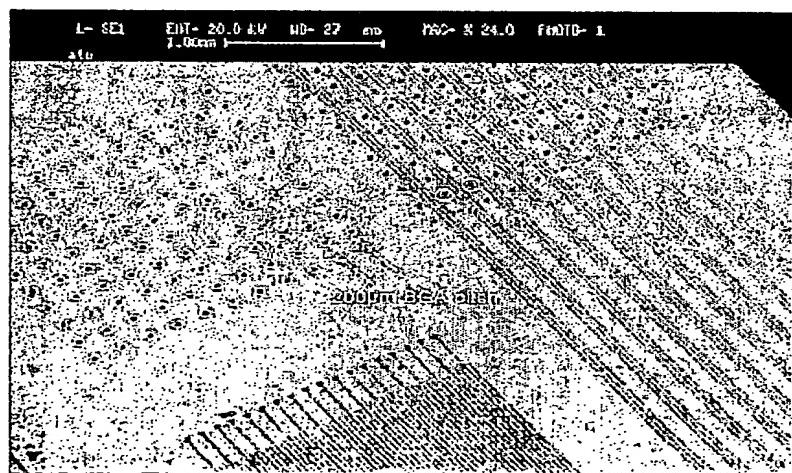


Fig. 10

BEST AVAILABLE COPY



Fig. 11

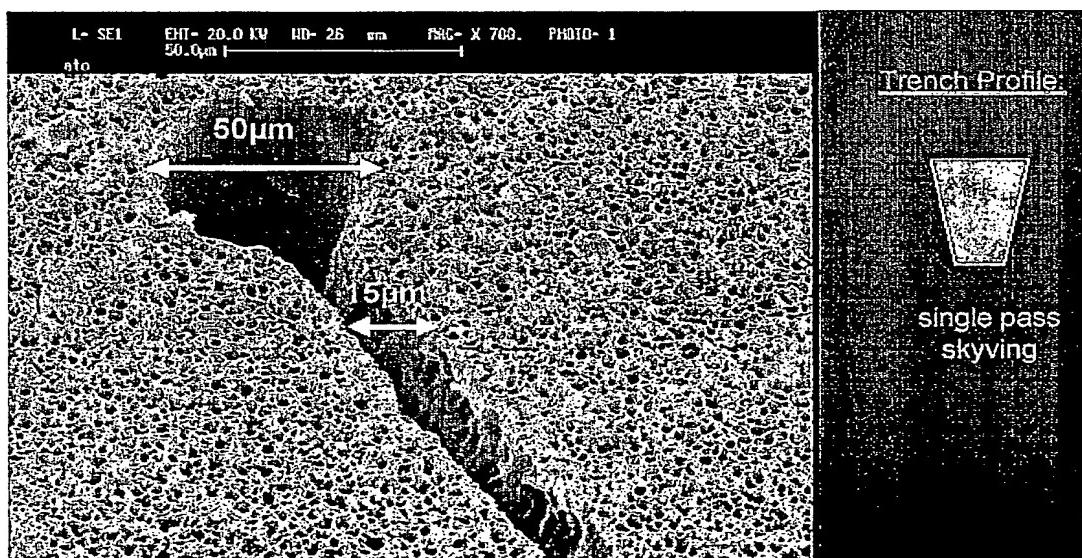
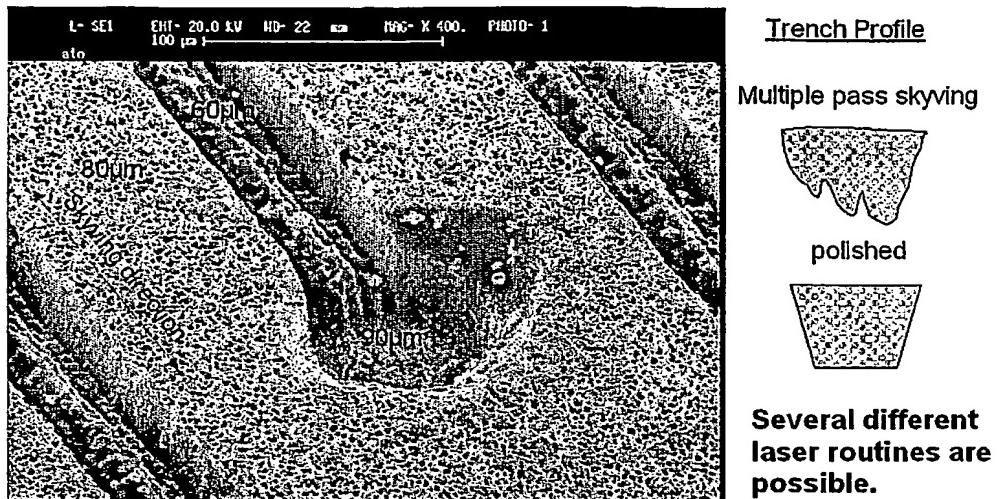
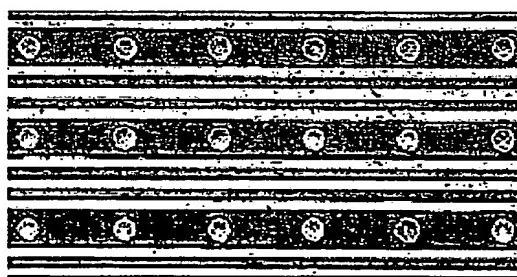


Fig. 12

BEST AVAILABLE COPY

Via² - Process**Multi pass skiving – before laser polish - 0.8 mm BGA****SEM – Detail of hole trench intersection****Fig. 13****Fig. 14****BEST AVAILABLE COPY**

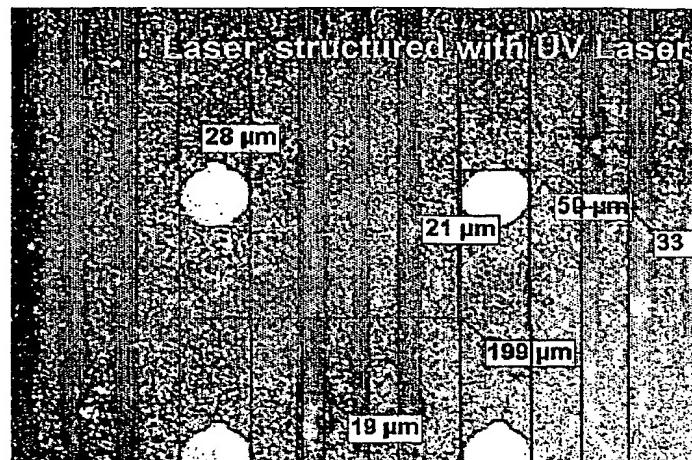


Fig. 15

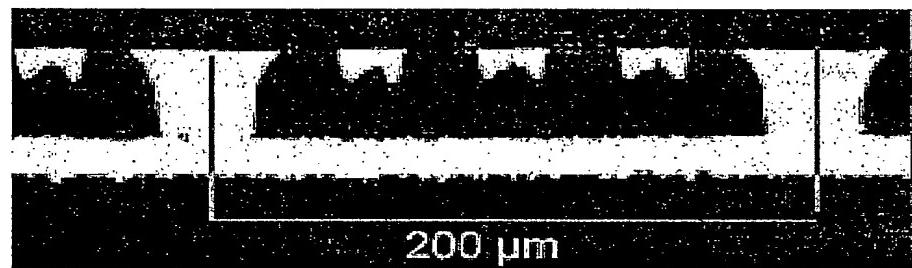


Fig. 16



Fig. 17

BEST AVAILABLE COPY

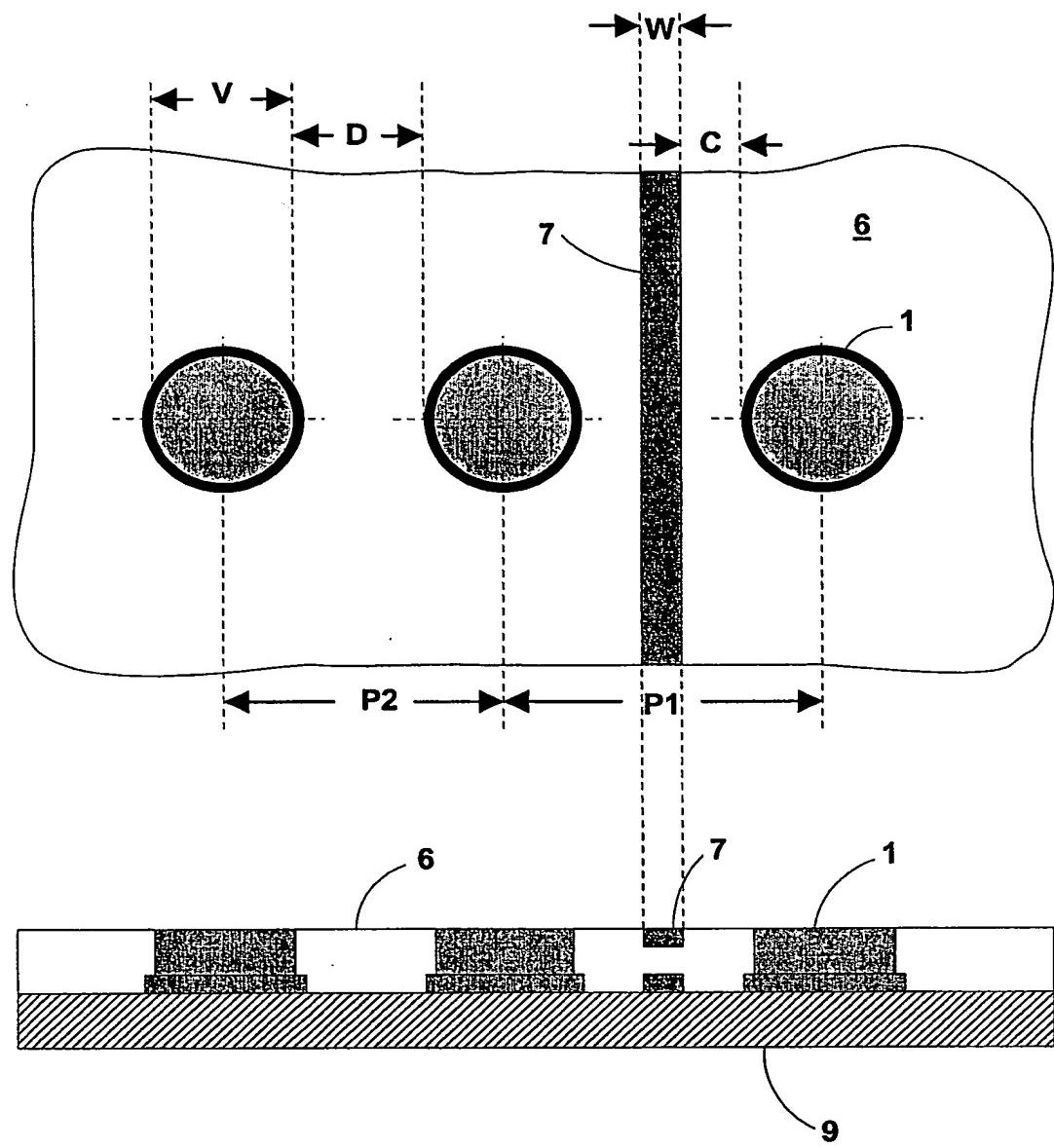


Fig. 18

BEST AVAILABLE COPY